# BAW56WT1G, SBAW56WT1G

# Dual Switching Diode, Common Anode

## Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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ANODE

## **MAXIMUM RATINGS** ( $T_A = 25^{\circ}C$ )

Rating	Symbol	Max	Unit
Reverse Voltage	V <sub>R</sub>	70	V
Forward Current	١ <sub>F</sub>	200	mA
Peak Forward Surge Current	I <sub>FM(surge)</sub>	500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## **THERMAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ )

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_{A} = 25^{\circ}C$	P <sub>D</sub>	200	mW
Derate above 25°C		1.6	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	625	°C/W
Total Device Dissipation Alumina Substrate (Note 2) $T_A = 25^{\circ}C$	P <sub>D</sub>	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

1. FR–5 = 1.0  $\times$  0.75  $\times$  0.062 in.

2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.

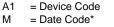


CATHODE

CATHODE

2





= Pb–Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
BAW56WT1G	SC–70 (Pb–Free)	3,000 / Tape & Reel
SBAW56WT1G	SC–70 (Pb–Free)	3,000 / Tape & Reel

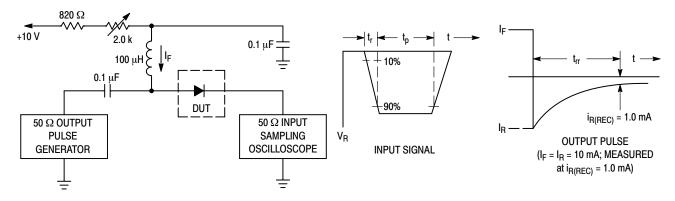
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Reverse Breakdown Voltage $(I_{(BR)} = 100 \ \mu A)$	V <sub>(BR)</sub>	70	_	V	
Reverse Voltage Leakage Current $(V_R = 25 \text{ V}, \text{ T}_J = 150^{\circ}\text{C})$ $(V_R = 70 \text{ V})$ $(V_R = 70 \text{ V}, \text{ T}_J = 150^{\circ}\text{C})$	IR	- - -	30 2.5 50	μΑ	
Diode Capacitance ( $V_R = 0, f = 1.0 \text{ MHz}$ )	CD	_	2.0	pF	
Forward Voltage $(I_F = 1.0 \text{ mA})$ $(I_F = 10 \text{ mA})$ $(I_F = 50 \text{ mA})$ $(I_F = 150 \text{ mA})$	V <sub>F</sub>	- - - -	715 855 1000 1250	mV	
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mA}, R_L = 100 \Omega, I_{R(REC)} = 1.0 \text{ mA}$ ) (Figure 1)	t <sub>rr</sub>	_	6.0	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



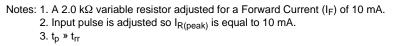


Figure 1. Recovery Time Equivalent Test Circuit

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# **TYPICAL CHARACTERISTICS**

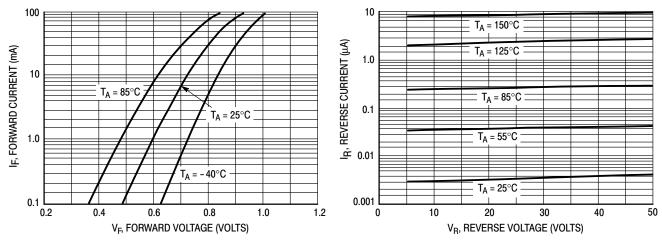


Figure 2. Forward Voltage

Figure 3. Leakage Current

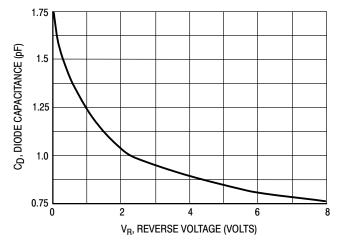
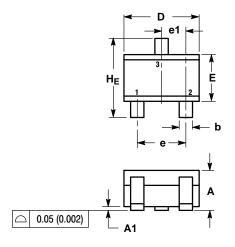


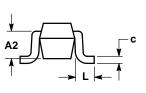
Figure 4. Capacitance

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### PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 **ISSUE N** 





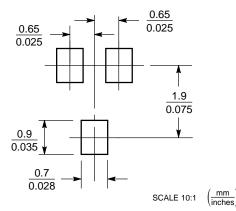
NOTES: DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.032	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2	0.70 REF				0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016	
с	0.10	0.18	0.25	0.004	0.007	0.010	
D	1.80	2.10	2.20	0.071	0.083	0.087	
E	1.15	1.24	1.35	0.045	0.049	0.053	
е	1.20	1.30	1.40	0.047	0.051	0.055	
e1	0.65 BSC			0.026 BSC			
L	0.20	0.38	0.56	0.008	0.015	0.022	
HE	2.00	2.10	2.40	0.079	0.083	0.095	

#### STYLE 4: PIN 1. CATHODE 2. CATHODE

3. ANODE

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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